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A novel heat-resistant resin-based adhesive for high-temperature alloy connection and repair

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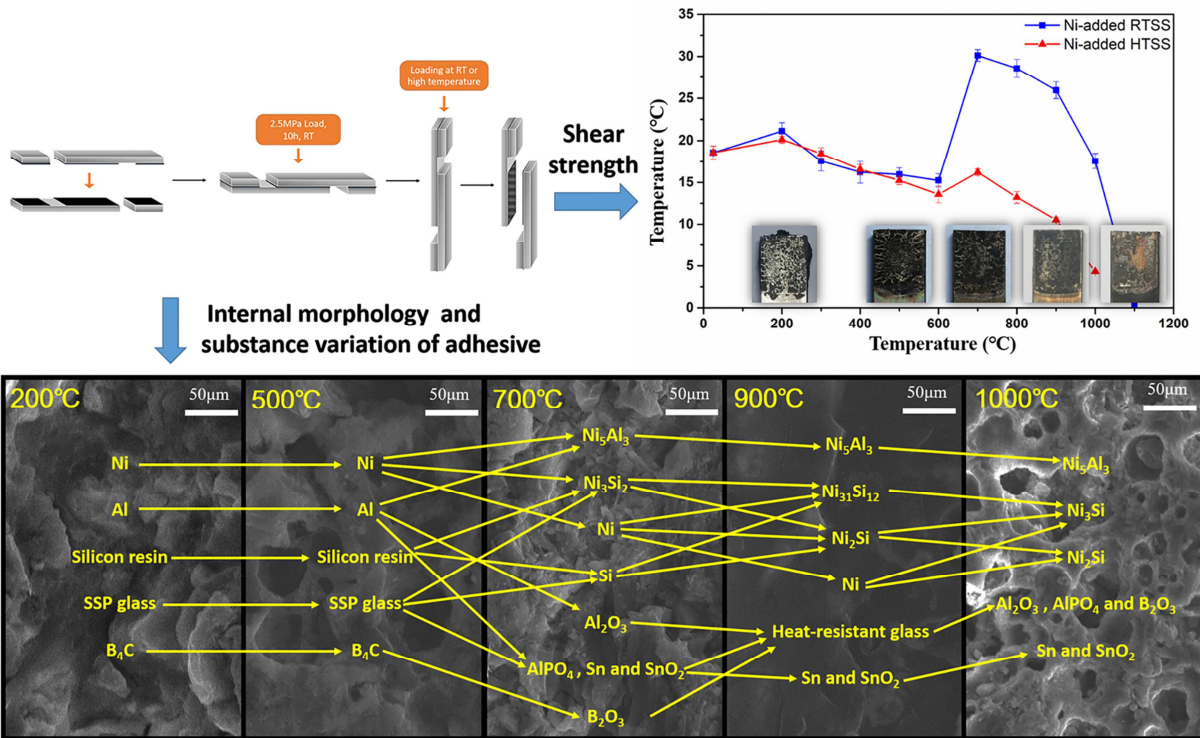
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